

**PATTERN FORMING METHOD, PATTERN FORMING APPARATUS,
AND DEVICE MANUFACTURING METHOD**

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ABSTRACT

A plurality of marks on a wafer (W) are detected while a wafer stage (WST) moves from a loading position where the wafer (W) is delivered onto the wafer stage (WST) to an exposure
10 starting position where exposure of the wafer (W) begins, with at least a part of an alignment system (ALG1, ALG2) also being moved, using the alignment system (ALG1, ALG2). Accordingly, the time required for mark detection can be reduced, therefore, it becomes possible to increase the throughput of the entire
15 exposure process.

Fig. 7A